

ABSTRACT

FABRICATION METHOD OF ACOUSTIC WAVE DEVICE

A fabrication method of an acoustic wave device includes: forming a metal layer between regions that are located on a piezoelectric substrate and in which acoustic wave chips are to be formed, at least a part of a region of the metal layer extending to an extension direction of a dicing line for separating the acoustic wave chips; and scanning the dicing line of the piezoelectric substrate by a laser beam so that the at least a part of the region of the metal layer is not irradiated with the laser beam.

FIG. 6A